


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	ADG/20/12358	
1.3 Title of PCI	Datasheet update for Maximum Operating Junction Temperature from 150°C to 175°C	
1.4 Product Category	STPS200170TV1Y Diode	
1.5 Issue date	2020-11-25	

2. PCI Team

2.1 Contact supplier	
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2.2 Change responsibility	
2.2.1 Product Manager	Stephane CHAMARD
2.1.2 Marketing Manager	Philippe LEGER
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
General Product & Design	Modification of datasheet :parameters/electrical specification (min./max./typ. values) and/or AC/DC specification	ST assy site in Morocco

4. Description of change

	Old	New
4.1 Description	Maximum Operating Junction Temperature @150°C	Maximum Operating Junction Temperature @175°C
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

5. Reason / motivation for change

5.1 Motivation	Allowing Tj max 175°C will give more margin for thermal customer design.
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	n/a
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7. Timing / schedule

7.1 Date of qualification results	2020-11-13
7.2 Intended start of delivery	2020-11-26
7.3 Qualification sample available?	Not Applicable

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)		
12358 Public product.pdf 12358 Datasheet update for Maximum Operating Junction Temperature.pdf		
10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STPS200170TV1Y	

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(1) ADG: Automotive & Discretes Group

<h2 style="text-align: center;">PCI</h2> <h3 style="text-align: center;">Product/Process Change Information</h3>									
<p style="text-align: center;">Datasheet update for Maximum Operating Junction Temperature from 150°C to 175°C</p>									
Notification number:	ADG/20/12358	Issue Date	2020 Nov 25th						
Issued by	Isabelle BALLON								
Product series affected by the change		STPS200170TV1Y							
<p>Reason for change</p> <p>Datasheet update for Maximum Operating Junction Temperature (Tj max) from 150°C to 175°C</p>									
<p>Effects of change</p> <p>Allowing Tj max 175°C will give more margin for thermal customer design.</p>									
<p>Product identification and traceability</p> <p>No changes from existing marking. Traceability will refer to the assembly date codes beginning of production schedule start.</p>									
Qualification complete date		W46-2020							
<p>Forecasted sample availability</p> <p>Not applicable</p>									
<p>Change implementation schedule</p> <table border="1" style="width: 100%;"> <thead> <tr> <th style="text-align: center;">Sales types</th> <th style="text-align: center;">Estimated production start</th> <th style="text-align: center;">Estimated first shipments</th> </tr> </thead> <tbody> <tr> <td style="text-align: center;">STPS200170TV1Y</td> <td colspan="2" style="text-align: center;"> Already in production Only datasheet update </td> </tr> </tbody> </table>				Sales types	Estimated production start	Estimated first shipments	STPS200170TV1Y	Already in production Only datasheet update	
Sales types	Estimated production start	Estimated first shipments							
STPS200170TV1Y	Already in production Only datasheet update								

Reliability Evaluation Report

Upgrade of STPS200170TV1Y
maximum junction temperature (Tj max) at 175°C

General Information		Locations	
Product Line	Rectifiers	Wafer fab	ST SINGAPORE
Product Description	Power Schottky rectifiers	Assembly plant	ST BOUSKOURA - MOROCCO
Product perimeter	STPS200170TV1Y	Reliability Lab	ST TOURS - FRANCE
Product Group	ADG		
Product division	Discrete & Filter		
Package	ISOTOP		
Maturity level step	QUALIFIED	Reliability assessment	PASS

DOCUMENT INFORMATION

Version	Date	Pages	Prepared by	Approved by	Comments
1.0	13-Nov-2020	6	Christophe GOIN	Julien MICHELON	Initial release

Note: This report is a summary of the reliability trials performed in good faith by STMicroelectronics in order to evaluate the potential reliability risks during the product life using a set of defined test methods.

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1 APPLICABLE AND REFERENCE DOCUMENTS

Document reference	Short description
JESD 47	Stress-Test-Driven Qualification of Integrated Circuits
JESD 94	Application specific qualification using knowledge based test methodology
JESD 22	Reliability test methods for packaged devices
MIL-STD-750C	Test method for semiconductor devices
AEC-Q005	Pb-Free Test Requirements

2 GLOSSARY

SS	Sample Size
PC	Pre-Conditioning
HTRB	High Temperature Reverse Bias
TC	Temperature Cycling
H3TRB	High Humidity High Temperature Reverse Bias
IOLT	Intermittent Operating Life Test
UHASt	Unbiased Highly Accelerated Stress Test
DPA	Destructive Physical Analysis (after TC and THB)
GD	Generic Data
SD	Solderability test
RSH	Resistance to Soldering Heat
THS	Temperature Humidity Storage
TJ max	Maximum junction temperature

3 RELIABILITY EVALUATION OVERVIEW

3.1 Objectives

The objective of this report is to validate that STPS200170TV1Y product can reach a maximum junction temperature of 175°C.

The involved products are listed in the table here below:

Product	Product Family	Package	Wafer Fab	Assembly Location
STPS200170TV1Y	POWER SCHOTTKY	ISOTOP	ST SINGAPORE	ST BOUSKOURA – MOROCCO

The test methodology follows ST internal procedure:

- Wafer level test to guarantee that there will be no deterioration of the products characteristics after exploring a maximum junction temperature of 175°C
- Package level test to guarantee that package materials can sustain an exploration of the maximum junction temperature of 175°C at die level

3.2 Conclusion

Qualification Plan requirements have been fulfilled without exception. Tests have shown that the devices behave correctly after exploring a maximum junction temperature of 175°C.

4 DEVICE CHARACTERISTICS

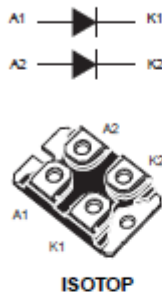
4.1 Device description

ST specification:



STPS200170TV1Y

Datasheet

Automotive 170 V, 2 x 100 A, high voltage power Schottky rectifier



Features

- AEC-Q101 qualified 
- PPAP capable
- Operating T_J from $-40\text{ }^{\circ}\text{C}$ to $+175\text{ }^{\circ}\text{C}$
- Negligible switching losses
- Low leakage current
- Avalanche rated
- Good trade-off between leakage current and forward voltage drop
- Insulated package ISOTOP comply with UL1557 insulation:
 - Insulated voltage: $2500\text{ V}_{\text{RMS}}$ sine
- ECOPACK2 compliant component

Applications

- DC/DC converter, especially in hybrid or electrical vehicles
- Secondary rectification
- LLC topologies
- Phase shift topologies

Description

This high voltage Schottky rectifier is suitable for high frequency switch mode power supplies.

Packaged in ISOTOP, the STPS200170TV1Y is intended for use in secondary rectification applications and more precisely in DC/DC converters in hybrid and electrical vehicles.

Product status link	
STPS200170TV1Y	
Product summary	
Symbol	Value
$I_{\text{F(AV)}}$	2 x 100 A
V_{RRM}	170 V
$T_J\text{ (max.)}$	175 $^{\circ}\text{C}$
$V_F\text{ (typ.)}$	0.63 V

4.2 Construction Note

STPS200170TV1Y	
Wafer/Die fab. information	
Wafer fab manufacturing location	ST SINGAPORE
Technology / Process family	Power Schottky Rectifier
Wafer Testing (EWS) information	
Electrical testing manufacturing location	ST SINGAPORE
Assembly information	
Assembly site	ST BOUSKOURA - MOROCCO
Package description	ISOTOP
Final testing information	
Testing location	ST BOUSKOURA - MOROCCO

5 TESTS RESULTS SUMMARY

5.1 Test vehicles

Lot #	Part Number	Package	Comments
L1	STPS200170TV1Y	ISOTOP	Qualification lot

Detailed results in below chapter will refer to these references.

5.2 Test plan and results summary

Test	Std ref.	Conditions	Steps / Duration	SS	Failure/SS
					L1
Die Oriented Tests					
Wafer level test to guarantee Tj max	ST internal specification	Ir, Vf parameters after 175°C exploration	-	30	0/30
Package Oriented Tests					
Package level test to guarantee Tj max	UL Certification 1557 (File E81734)	201°C	5Khrs	21	0/21



Public Products List

Public Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCI Title : Datasheet update for Maximum Operating Junction Temperature from 150°C to 175°C

PCI Reference : ADG/20/12358

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STPS200170TV1Y		
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